

SiP Digital Layout



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Title: SiP Digital Layout - v16.0	Type: Instructor Led Course
Product Number: 86090	Price: \$ 3,500.00
Length: 5 Day(s)	
Description:	This course takes you through a complete design flow of a System in Package (SiP) design, from defining the module outline through placing components; defining a netlist; placement; routing; and documentation and manufacturing output. The course covers the complete design flow for a flip chip and wire bonded stacked die module using the Cadence® SiP Digital Layout software.
Learning Objectives:	In this course you will learn to: <ul style="list-style-type: none">• Develop a process flow to suit your design needs.• Create a cross section and design constraints in your SiP Layout database.• Add a co-design die to your SiP Layout and edit that co-design die in the IO Planner tool.• Wire bond a stacked die design.• Use the 3D Viewer to view and check your design in three dimensions.• Route a SiP design using interactive and automatic methods.• Generate a variety of manufacturing outputs for your SiP design.
Agenda:	<p>Day 1</p> <ul style="list-style-type: none">• User Interface• Creating IO Components• Creating Standard Die• Creating and Editing Co-Design Die <p>Day 2</p> <ul style="list-style-type: none">• Creating Co-Design Die• Design Constraints• Die Stack Editing• 3D Viewing <p>Day 3</p> <ul style="list-style-type: none">• Adding Discrete Components• Power and Ground Rings• Wire Bonding <p>Day 4</p> <ul style="list-style-type: none">• Routing• Conductor Planes• Degassing <p>Day 5</p> <ul style="list-style-type: none">• Vendor Preparation• Reports• Manufacturing Data
Audience:	This course is for SiP, SCM, MCM, and PCB design engineers.
Special Notes:	This course requires either the Cadence SiP Digital Layout GXL product or the Cadence RF Layout GXL product.
Prerequisites:	<ul style="list-style-type: none">• You should have a working knowledge of single and/or SiP design and construction.• You should be familiar with foundry design guidelines.• You should have a basic understanding of the UNIX or Windows operating systems.
Related Courses:	Allegro Package Designer Allegro High-Speed Constraint Management

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